PRODUCT ADVANTAGE

Excellent Pull Strength at 285°C
High Temperature Applications
(>300°C)
Removes Additional Gluing Processes
Excellent Process Compatibility
High Reliability
100% Reworkable

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OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

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SMT 256EP
SOLDER JOINT ENCAPSULANT PASTE
OVERVIEW
Preferred by global leaders in the electronics manufacturing industry
SMT 256EP is capable of being used at high temperatures for double reflow applications and can prevent components from falling off during this process.

**Availability**
- SMT 256EP T4: Printing
- SMT 256EP T6: Dispense (#27)
- SMT 256EP T6: Dispense (#30)

The YINCAE® SMT 256EP Solder Joint Encapsulant paste is a combination of solder paste and a solder joint encapsulant, and is designed to enhance solder joint reliability and eliminate solder joint cracking in CSP, BGA, flip chips and POP microchip applications. This product removes metal oxide and allows individual solder joints to be formed, encapsulated by 3-D polymer network.

Compared to conductive solder adhesives, SMT 256EP offers a higher and more stable thermal and electrical conductivity.

Contact YINCAE at info@yincae.com for detailed specifications & customization for your specific product requirements.